Semiconductor Device Type: C7X-SOT-23-5-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				1.05	100.00%	7.00%		
	Silicon	7440-21-3	1.05		100.00%		7.00%	70000
Mold Compound				11.43	100.00%	76.20%		
	Phenolic Resin	Trade Secret	0.91		8.00%		6.10%	60960
	Silica (Fused)	60676-86-0	9.20		80.50%		61.34%	613410
	Carbon Black	1333-86-4	0.06		0.50%		0.38%	3810
	o-Cresol-epichlorohydrin-formaldehyde Copolymer	29690-82-2	0.34		3.00%		2.29%	22860
	Epoxy Resin	Trade Secret	0.91		8.00%		6.10%	60960
Plating and Anode Ball				0.15	100.00%	1.00%		
	Lead	7439-92-1	0.00		0.05%		0.00%	5
	Tin	7440-31-5	0.15		99.95%		1.00%	9995
Lead Frame				2.19	100.00%	14.60%		
	Iron	7439-89-6	0.05		2.37%		0.35%	3455
	Lead	7439-92-1	0.00		0.01%		0.00%	15
	Phosphorus	7723-14-0	0.00		0.08%		0.01%	121
	Copper	7440-50-8	2.13		97.42%		14.23%	142270
	Zinc	7440-66-6	0.00		0.13%		0.02%	184
Lead Frame Plating				0.01	100.00%	0.10%		
	Silver	7440-22-4	0.01		100.00%		0.10%	956
Die Attach				0.12	100.00%	0.80%		
	2,2'-[[2-(2-Oxiranylmethoxy)-1,3-phenylene]bis(methylene)]bis[oxirane]	13561-08-5	0.01		10.00%		0.08%	800
	Silver	7440-22-4	0.08		70.00%		0.56%	5600
	Formaldehyde, Polymer with 2-(chloromethyl)oxirane and Phenol	9003-36-5	0.01		10.00%		0.08%	800
	Dimer Acid Diglycidyl Ester	68475-94-5	0.01		10.00%		0.08%	800
Bond Wire				0.04	100.00%	0.30%		
	Gold	7440-57-5	0.04		100.00%		0.30%	3000
Totals			**15.00**	**15.00**		**100.00%**	**100.00%**	**1000000**

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